



Product End-of-Life Instructions

PRODUCT FAMILY

Power Edge Servers

PURPOSE

The intent of this document is to provide guidance to recyclers on the presence of materials and components at the product / family level, as required by the EU WEEE Directive 2012/19/EU. This document should also help direct recyclers to proper methods for removing parts and general product disassembly instructions.

PRODUCT DISASSEMBLY INSTRUCTIONS

Most parts can be removed easily by hand. In some cases, common household tools such as Philips and/or flat-head screw drivers may be necessary. To remove discrete components such as the electrolytic capacitors, needle-nose pliers may be helpful. Instructions for removing parts in each product can be found in the User Documentation originally provided with the product. This documentation can be found online:

http://www.dell.com/support/home/us/en/19/products/ser_stor_net/poweredge

PRODUCT MATERIAL INFORMATION

The following substances, preparations, or components should be disposed of or recovered separately from other WEEE in compliance with Article 4 of EU Council Directive 75/442/EEC.

Batteries	Mercury	Dell does not use internal batteries based on Mercury (Hg) and its compounds.
	Cadmium	Dell does not use internal batteries based on Cadmium (Cd) and its compounds.
	Lead	Dell does not use internal batteries based on Lead (Pb) and its compounds.
	Other	Dell servers use Lithium Primary Coin Cells. Depending on the feature set, some may also include Lithium Ion secondaries. Additional features such as add in PERC, RAID, or DRAC cards may include a Lithium Ion Button Cell or Nickel Metal Hydride batteries.
Mercury	Lamps, Bulbs, and other Lighting Applications	Product does not contain a Mercury based lamp or bulb.
	Other Uses	Other parts used in Dell products can not contain intentionally added Mercury.
Liquid Crystal Displays (LCD) - > 100 cm ²		Product does not contain an LCD greater than 100 cm ² .
Cathode Ray Tubes (CRT)		Product does not contain a CRT



<p>Plastic containing Brominated flame retardants other than in PCB / PCA</p>	<p>This product may contain plastic parts greater than 25 grams. Many of these parts are bromine free. Regardless, these parts are labeled (usually molded directly into the plastic) per ISO 11469.</p> <p>A typical label would look like: > Polymer Abbreviation - FR(#) < i.e. > PC+ABS FR(40) <</p> <p>Flame retardant codes (FR(#)) are given in ISO 1043-4. Codes for some Brominated flame retardants: 14 aliphatic/alicyclic Brominated compounds 15 aliphatic/alicyclic Brominated compounds in combination with antimony compounds 16 aromatic Brominated compounds (excluding Brominated diphenyl ether and biphenyls) 17 aromatic Brominated compounds (excluding Brominated diphenyl ether and biphenyls) in combination with antimony compounds 22 aliphatic/alicyclic chlorinated and Brominated compounds 42 Brominated organic phosphorus compounds</p>
<p>Capacitors with PCB's</p>	<p>Dell does not use capacitors with PCB</p>
<p>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</p>	<p>Present in Dell Server as system board (mother board), network card, mezzanine card.</p>
<p>chlorofluorocarbons (CFC), hydrochlorofluorocarbons (HCFC) or hydrofluorocarbons (HFC), hydrocarbons (HC)</p>	<p>Dell products do not contain Ozone depleting substance (Class 1 and Class II CFCs and HCFCs)</p>
<p>External Electrical cables</p>	<p>External cables may be present.</p>
<p>Electrolyte capacitors (height > 25mm, diameter > 25mm)</p>	<p>Electrolytic capacitors (height and/or diameter greater than 25mm) are not used on Dell motherboards. However, these capacitors are often present in power supply units (silver box).</p>
<p>Asbestos and its compounds</p>	<p>Parts used in Dell products cannot contain asbestos or its compounds</p>
<p>Refractory ceramic fibers</p>	<p>Parts used in Dell products cannot contain refractory ceramic fibers</p>
<p>Radio-active substances</p>	<p>Parts used in Dell products cannot contain Radio-active substances.</p>
<p>Beryllium and its compounds (including Beryllium Oxide)</p>	<p>Beryllium may be present in electronic components as a copper beryllium alloy, which contains less than 2% beryllium. CuBe alloys may be used in various components such as connectors, switches, relays, current carrying springs, integrated circuit sockets, and RF shielding.</p>



Gasses - which fall under Regulation (EC) 2037/2000 and all hydrocarbons (HC)	Parts used in Dell products do not contain gasses which fall under Regulation (EC 2037/2000) and all hydrocarbons (HC).
Components with pressurized gas which need special attention (Pressure > 1,5bar)	Product does not contain parts with pressurized gas.
Liquids	This product may contain a heatsink heat pipe. Heat pipes contain a very small amount of very pure water.

DELL CORPORATE ENVIRONMENTAL INFORMATION

Information on Dell's Environmental initiatives, policies, programs and goals can be found at www.dell.com/environment.